



PIN DESCRIPTION and PAD DIMENSIONS

Name	I/O	Description	Pad dimensions [µm]	
			X	Y
INHN	I	Output state control input. High impedance when LOW (oscillator stops). Power-saving pull-up resistor built-in.	151	277
XT	I	Amplifier input	238	131
XTN	O	Amplifier output	512	131
VSS	-	Ground	588	345
Q	O	Output. Output frequency (f _Q , f _Q /2, f _Q /4, f _Q /8, f _Q /16) determined by internal connection	588	548
VDD	-	Supply voltage	131	548

Instructions:

- A. Standard process flow for die-attach and wire bond of semiconductor die in ceramic SMD is acceptable.
- B. Final assemblies are nitrogen purged and vacuum packed for transportation. Trays used for shipping ceramic carriers are acceptable.
- C. Label shall at minimum include part number, quantity, and Lot Code.
- D. Part number shall take the form ASM5070-5014ALx where x = version number 1 through 5.

- ASM5070-CF5014AL1
- ASM5070-CF5014AL2
- ASM5070-CF5014AL3
- ASM5070-CF5014AL4
- ASM5070-CF5014AL5

Item ID	Description	Qty / Unit
S5070CLK8	4-pad 5mm x 7mm ceramic base	1
5014ALx-2 *	IC Oscillator 220µm thick	1

This ceramic base package has different interior layout than Rev A, however the package size and height and Kovar ring are specified the same as Rev A.

Final pad orientation remain the same.

Pad 1 = Enable/Disable
 Pad 2 = VSS or Ground
 Pad 3 = Q or output
 Pad 4 = VDD

Revision	Date	Reason
B	2017-04-22	Package Base change (Same form-fit-function)
A	2009/10/14	Update Instruction C Time/Temp to include approved alternate
-	2009/8/10	Original Issue (Type II B)



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 Revision: B